

ABSTRACT

The surface of a material for an electronic device
is flattened by irradiating the surface of the material
5 with at least part of plasma components, while supplying
a liquid to the surface of the material for an electronic
device. There are provided a method of treating the
surfaces for favorably flattening the surface of the
material for an electronic device or of the substrate for
10 an electronic device, while suppressing damage to the
material or to the substrate, and an apparatus for
treating the surfaces.